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MEMS PACKAGING MARKETS AND TRENDS

FIRST EDITION

**A Strategic Report on Device-Level Packaging
of MEMS Semiconductor Products**

Report Highlights

- **Technology Reviews**
 - ◆ **Microphones**
 - ◆ **Accelerometers/Gyroscopes**
 - ◆ **Pressure Sensors**
 - ◆ **Actuators**
 - ◆ **Others**
- **Product and Company Highlights**
- **Market Analysis and Forecasts, 2007–2012**



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MEMS PACKAGING MARKETS AND TRENDS

Synopsis

Although it is a relatively new technology, the MEMS (micro-electromechanical systems) market for actuators, accelerometers, gyroscopes, pressure sensors, and microphones has become a substantial force in the semiconductor industry. Other MEMS products also show promise.

The manufacturing processes of integrated circuits (ICs) are the model used for the manufacture of MEMS devices. Not only are MEMS being created on wafers, but they are being combined in most cases with ICs within variations of standard IC packages. As such, MEMS package assembly has become a topic of great interest to the overall semiconductor packaging industry.

Electronic Trend Publications (ETP) in its report, **MEMS Packaging Markets and Trends**, uses information from semiconductor industry insiders to present the most realistic picture available regarding packaging technologies and markets for key MEMS products.

Chapter 1 of the report explains the scope and methodology of the report, while Chapter 2 summarizes the report's key market data.

Chapter 3, **Technical Trends**, presents a concise technical overview of the MEMS market. Topics include applications, device fabrication methods, and packaging options.

Chapter 4, **Product and Company Highlights**, presents the newest packaging products and latest research from over 70 companies and organizations. This presentation is organized into 17 categories of products and services.

Chapter 5, **Forecasts**, presents information on the sensor and actuator products that define the majority of the robust MEMS market. Products include accelerometers and gyroscopes, pressure sensors, microphones, and various actuators.

Forecasts of these MEMS markets include units, package assembly prices, average I/O counts, average assembly costs, and package assembly revenue. The MEMS packaging market is poised for substantial growth in the coming years.

MEMS Packaging Markets and Trends will provide you with an effective and economical tool for assessing the future of the MEMS packaging market. Please take a few moments to review the report's outline on the following pages. The report is delivered by email as a single-user PDF file. The report sells for \$1995, with extra single-user licenses at \$250 each. Corporate licensing is available—contact us for pricing.

About the Author

Sandra Winkler is the senior analyst for IC packaging at Electronic Trend Publications (ETP). She began her analyst career as an independent consultant to the telecommunications industry nearly 20 years ago. Since 1995, Ms. Winkler has authored all of ETP's widely cited reports on IC packaging. She has spoken at numerous industry conferences and is a contributing editor for Chip Scale Review magazine. Ms. Winkler has an MBA from Santa Clara University.

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